

SOT1139-1

plastic ball grid array package; 582 balls, 1 mm pitch, 27 mm x 27 mm x 1.87 mm body

11 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA582
Package type industry code	BGA582
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MS-034 Compliant
Mounting method type	S (surface mount)
Issue date	26-05-2009
Manufacturer package code	SOT1139

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	26.8	27	27.2	mm
package width	26.8	27	27.2	mm
seated height	2.22	2.37	2.52	mm
package height	1.72	1.87	2.02	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	582	-	



2 Package outline

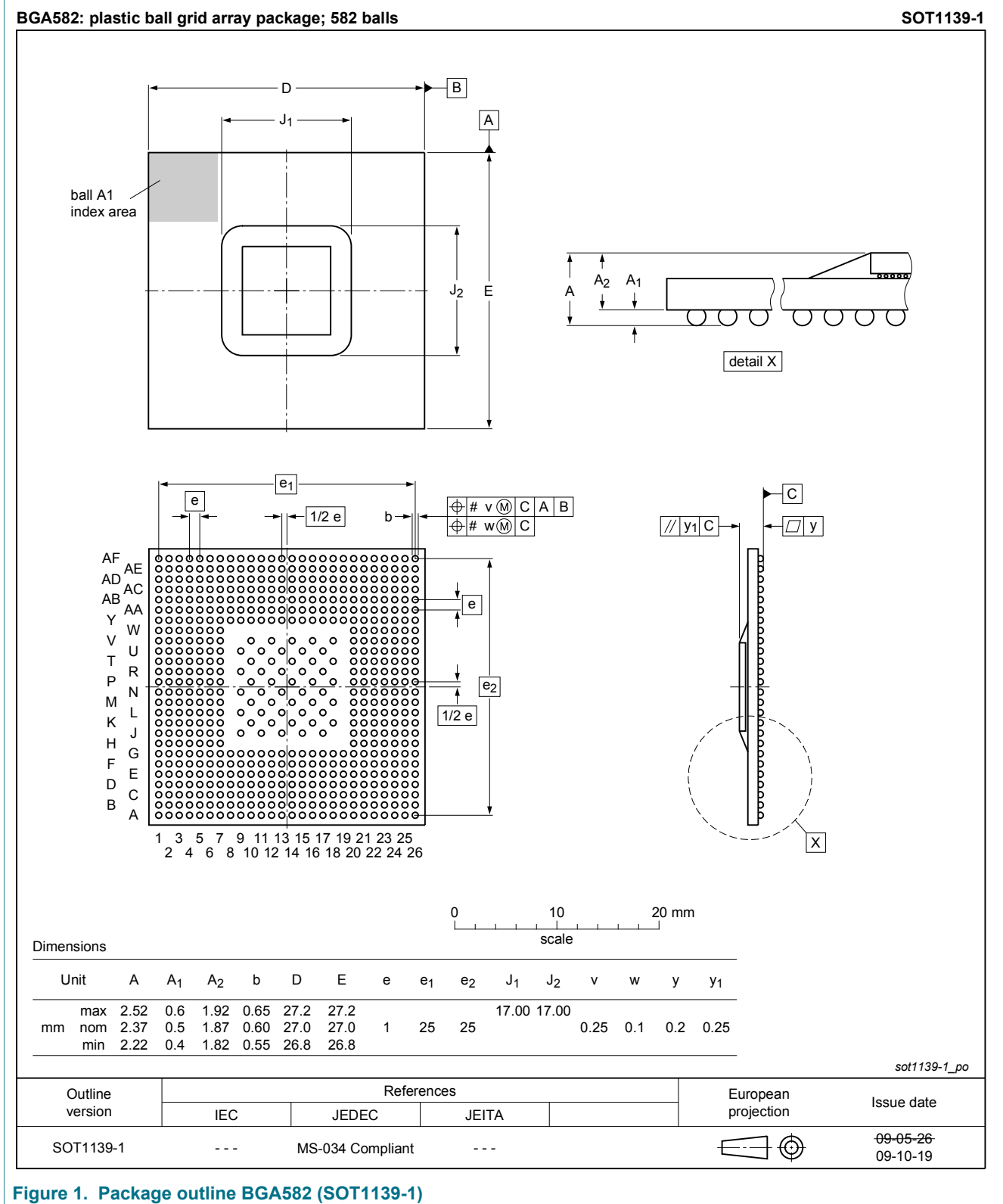


Figure 1. Package outline BGA582 (SOT1139-1)

3 Legal information

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